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Kretskort – Del 2: Grupp-specifikation – Lödda ytmonterade kretskort

*Printed board assemblies –
Part 2: Sectional specification –
Requirements for surface mount soldered assemblies*

Som svensk standard gäller europastandarden EN 61191-2:2017. Den svenska standarden innehåller den officiella engelska språkversionen av EN 61191-2:2017.

Nationellt förord

Europastandarden EN 61191-2:2017

består av:

- **europastandardens ikraftsättningsdokument**, utarbetat inom CENELEC
- **IEC 61191-2, Third edition, 2017 - Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies**

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Tidigare fastställd svensk standard SS-EN 61191-2, utgåva 2, 2013, gäller ej fr o m 2020-10-13.

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Postadress: Box 1284, 164 29 KISTA
Telefon: 08 - 444 14 00.
E-post: sek@elstandard.se. Internet: www.elstandard.se

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Box 1284
164 29 Kista
Tel 08-444 14 00
www.elstandard.se

English Version

**Printed board assemblies - Part 2: Sectional specification -
Requirements for surface mount soldered assemblies
(IEC 61191-2:2017)**

Ensembles de cartes imprimées - Partie 2: Spécification
intermédiaire - Exigences relatives à l'assemblage par
brasage pour montage en surface
(IEC 61191-2:2017)

Elektronikaufbauten auf Leiterplatten -
Teil 2: Rahmenspezifikation - Anforderungen an gelötete
Baugruppen in Oberflächenmontage
(IEC 61191-2:2017)

This European Standard was approved by CENELEC on 2017-06-27. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 91/1386/CDV, future edition 3 of IEC 61191-2, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61191-2:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2018-04-13
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-10-13

This document supersedes EN 61191-2:2013.

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Endorsement notice

The text of the International Standard IEC 61191-2:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-20	NOTE	Harmonized as EN 60068-2-20.
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58.
IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1.
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2.
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3.
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4.
IEC 61188-5-5	NOTE	Harmonized as EN 61188-5-5.
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-6.
IEC 61188-7	NOTE	Harmonized as EN 61188-7.
IEC 61189-2	NOTE	Harmonized as EN 61189-2.
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2.
IEC 61193-1	NOTE	Harmonized as EN 61193-1.
IEC 61193-3	NOTE	Harmonized as EN 61193-3.
IEC 62326-1	NOTE	Harmonized as EN 62326-1.
IEC 62326-4	NOTE	Harmonized as EN 62326-4.
IEC 62326-4-1	NOTE	Harmonized as EN 62326-4-1.
ISO 9001	NOTE	Harmonized as EN ISO 9001.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61191-1	-	Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN 61191-1	-
IPC-A-610	-	Acceptability of Electronics Assemblies	-	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED BOARD ASSEMBLIES –**Part 2: Sectional specification –
Requirements for surface mount soldered assemblies**

FOREWORD

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International Standard IEC 61191-2 has been prepared by IEC technical committee 91: Electronics assembly technology.

This third edition cancels and replaces the second edition published in 2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) the requirements have been updated to be compliant with the acceptance criteria in IPC-A-610F;
- b) some of the terminology used in the document has been updated;
- c) references to IEC standards have been corrected;
- d) five termination styles have been added.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1386/CDV	91/1429/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 61191 under the general title *Printed board assemblies* can be found in the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

PRINTED BOARD ASSEMBLIES –

Part 2: Sectional specification – Requirements for surface mount soldered assemblies

1 Scope

This part of IEC 61191 gives the requirements for surface mount solder connections. The requirements pertain to those assemblies that are totally surface mounted or to the surface mounted portions of those assemblies that include other related technologies (e.g. through-hole, chip mounting, terminal mounting, etc.).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61191-1, *Printed board assemblies – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies*

IPC-A-610, *Acceptability of Electronic Assemblies*